GET READY FOR SOMETHING INCREDIBLE IN YOUR NEXT SMARTPHONE

The World's 1st TSMC 4nm-class Smartphone Chip
The MediaTek Dimensity 9000 leads the industry by embracing leading-edge TSMC N4 (4nm-class) production – the most advanced and power efficient chip-making process ever.

Cortex-X2 over 3GHz
The Dimensity 9000 uses new Armv9 architecture CPUs to deliver unparalleled performance.
- Ultra-Core - 1x Arm Cortex-X2 at 3.05GHz
- Super-Cores - 3x Arm Cortex-A710 up to 2.85GHz
- Efficiency Cores - 4x Arm Cortex-A510
- LPDDR5x 7500Mbps support

Powerful Imaging Processors and Impressive HDR Cameras
A flagship 18-bit HDR-ISP design gives users the first opportunity to capture HDR video on three cameras simultaneously, while also assuring exceptional power efficiency.
- Most Powerful 9Gpixel/s ISP
- World’s 1st simultaneous triple camera 18-bit HDR video recording (three cameras recording with three exposures per frame)
- World’s 1st 320MP camera support for smartphones

5th Generation AI processor
Our new AI processing unit (APU) is designed to achieve maximum effective performance in AI-multimedia, gaming, camera, and social video experiences.
- Up to 4X power efficiency upgrade vs last generation
- Leading performance in AI

Amp Your Gaming
We’ve built the Dimensity 9000 with the latest Arm Mali-G710 graphics processor and also introduced a new raytracing SDK that will enable developers to bring exciting new graphics techniques and visual enhancements to their Android titles.
- World’s 1st Arm Mali-G710 MC10 graphics processor
- Industry’s 1st raytracing SDK using Vulkan for Android
- 180Hz FullHD+ display support

Leading 3GPP Release-16 5G Smartphone Modem
The Dimensity 9000 integrates the only 5G smartphone modem with 3GPP Release-16 standard technology into the chip, amplifying sub-6GHz performance to go faster and further than ever before.
- 3CC Carrier Aggregation (300MHz) 7Gbps downlink – incredible peak performance exclusively from sub-6GHz
- World’s 1st R16 UL Enhancement – the only 5G smartphone modem to support R16 UL Tx Switching for both SUL and NR UL-CA based connections
- Leading MediaTek 5G UltraSave 2.0 – new generation power saving enhancement suite

Latest Connectivity & Wireless Audio
MediaTek engineers have boosted Wi-Fi performance to make it as smooth as possible in key things like gaming, streaming media and video conferencing.
- World’s 1st Bluetooth 5.3 support in smartphones
- Wi-Fi 6E 2x2 (BW160): up to 2X better performance efficiency than previous generation and support for the latest 6GHz connectivity
- Bluetooth LE Audio-ready technology with Dual-Link True Wireless Stereo Audio
- New Beidou III-B1C GNSS support

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https://www.mediatek.com/Dimensity-9000